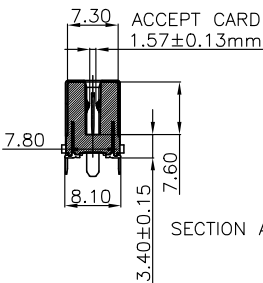
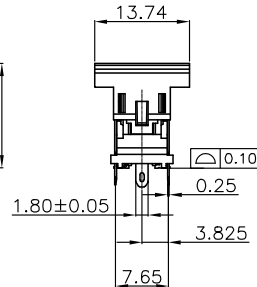
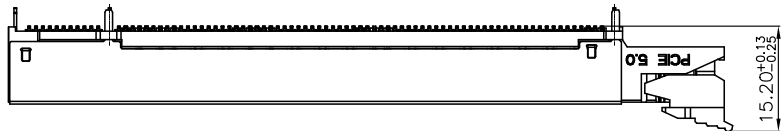
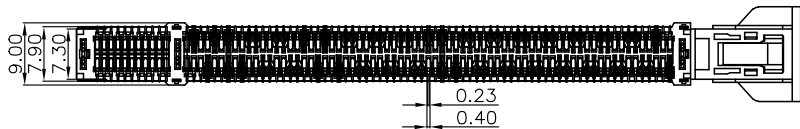
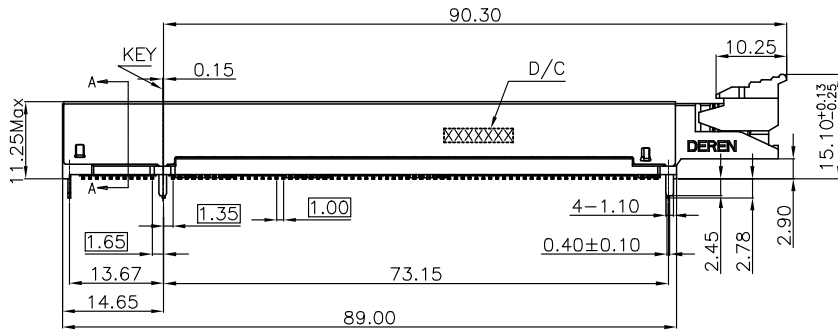
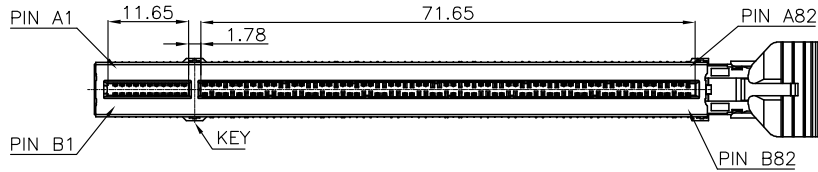
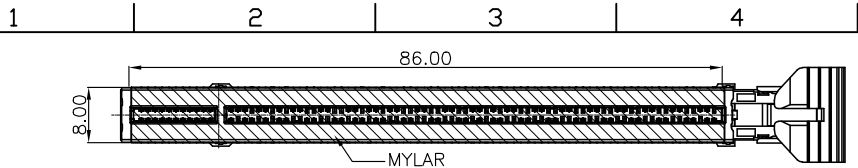


HF
Halogen Free



REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
X1			PRELIMINARY	2022.03.15	Chen

NOTES:

PRODUCT MEETS CONTROLLED SUBSTANCES SPEC. ROHS 2.0

1. MATERIAL:

- 1.1 HOUSING:HIGH TEMPERATURE PLASTIC, UL94V-0; COLOR: BLACK
- 1.2 OTHER CONTACT:COPPER ALLOY
- 1.3 EAR:HIGH TEMPERATURE PLASTIC, UL94V-0; COLOR: BLACK
- 1.4 GND CONTACT:COPPER ALLOY
- 1.5 HOOK:STAINLESS STEEL
- 1.6 SHELL:STAINLESS STEEL
- 1.7 GROUND PLATE:STAINLESS STEEL

2. FINISH:

- 2.1 OTHER CONTACT:GOLD PLATING(SEE PART NUMBER) ON CONTACT AREA.
2.54um[100u"] MIN. MATTE-TIN PLATING ON SOLDER TAIL AREA.
1.27um[50u"] MIN. NICKEL UNDERPLATING OVER ALL.
- 2.2 GND CONTACT:0.076um[3u"]Au PLATING ON CONTACT AREA.
2.54um[100u"] MIN. MATTE-TIN PLATING ON SOLDER TAIL AREA.
1.27um[50u"] MIN. NICKEL UNDERPLATING OVERALL.
- 2.3 HOOK:1.27um[50u"] MIN. NICKEL UNDERPLATING OVER ALL,100u" MATTE TIN PLATING OVER NICKEL AT TAIL.
- 2.4 SHELL:30u"MIN. NICKEL PLATING OVERALL

3.RECOMMENDED PROCESS:IR REFLOW 260'±5',3~5s

4.DATE CODE : YYWDLX (YY: YEAR, WW: WEEK, D: DAY,

L: PRODUCTION LINE CODE, X: MANUFACTURE CODE)

5.PART NUMBER DESCRIPTION:

564ZD4 -017H * * * *

PACKING CODE: 1:TRAY
2:REEL
3:HARD TRAY

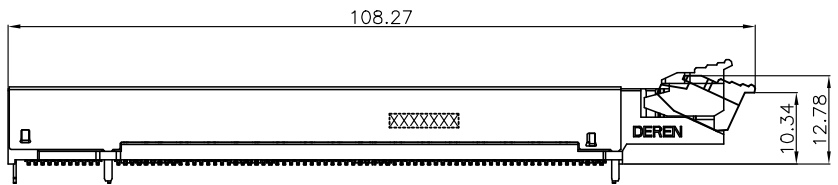
HOUSING COLOR: 1:BLACK 2:WITHE 3.BLUE

RIDGE&POS CODE:

- 1.HOUSING POST&WITH RIDGE
- 2.HOUSING POST&WITHOUT RIDGE
- 3.BOARD LOCK&WITH RIDGE
- 4.BOARD LOCK&WITHOUT RIDGE

PLATING CODE: 1: G/F
2: 15u" Min
3: 30u" Min

HALOGEN CODE: H: HALOGEN FREE



DIM	TOL	DIM	TOL
x.	±0.30	x.	±2'
.x	±0.25	.x	±1'
.xx	±0.20		



DEREN

SHENZHEN DEREN ELECTRONIC CO., LTD

DRAW NO.
SC21072**

CUSTOMER DRAWING	DATE
DESIGN: Chen	2022.03.15
CHECK: Bill.Lin	2022.03.15
APPROVAL: Smark.Huo	2022.03.15

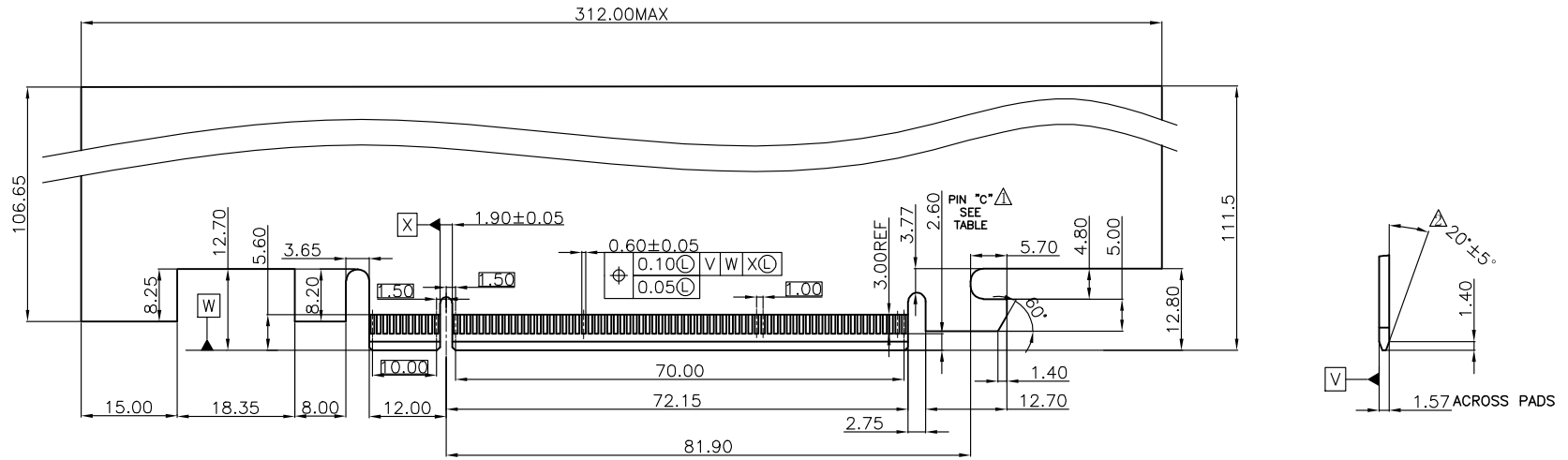
TITLE: PCI-E 5.0 SMT TYPE 164PIN WITH EAR&DIP HOOK&SHELL.

P/N:	SEE TABLE
SHEET: 1/3	
SCALE: 1:1	UNIT: mm

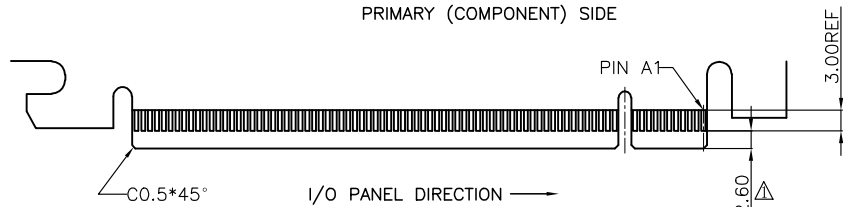
HF
Halogen Free



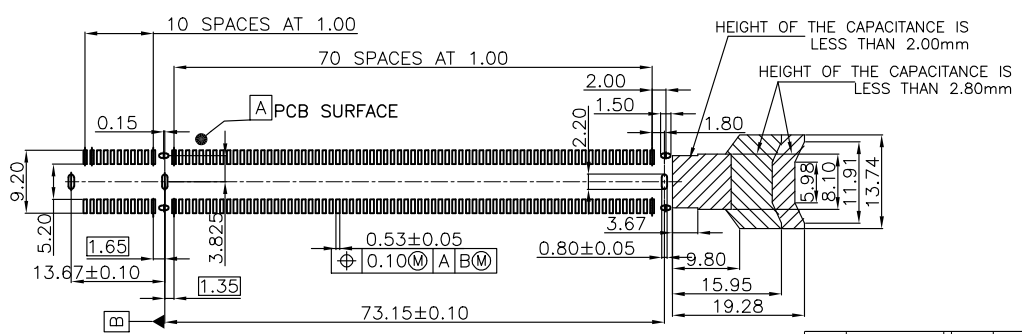
PIN DEFINITION		PIN DEFINITION	
GND-GND CONTACT		GROUND&OTHER CONTACT	
Side B	GND	Side A	GND
Pin#	Name	Pin#	Name
1	+12V	1	PRSn7
2	+12V	2	+12V
3	+12V	3	+12V
4	GROUND	4	GROUND
5	SMBCLK	5	JTAG2
6	SMBDAT	6	JTAG3
7	GROUND	7	JTAG4
8	3.3V	8	JTAG5
9	JTAG1	9	+3.3V
10	+3.3Vaux	10	+3.3V
11	WAKE#	11	PERSt#
12	CLKREF#	12	GROUND
13	GND	13	REFCLK+
14	PETp0	14	REFCLK-
15	PETn0	15	GND
16	GND	16	PERp0
17	PRSn2#	17	PERn0
18	GND	18	GND
19	PETp1	19	MFC
20	PETn1	20	GND
21	GND	21	PERp1
22	GND	22	PERn1
23	PETp2	23	GND
24	PETn2	24	GND
25	GND	25	PERp2
26	GND	26	PERn2
27	PETp3	27	GND
28	PETn3	28	GND
29	GND	29	PERp3
30	PWRSt#	30	PERn3
31	PRSn2#	31	GND
32	GND	32	RSVD
33	PETp4	33	RSVD
34	PETn4	34	GND
35	GND	35	PERp4
36	GND	36	PERn4
37	PETp5	37	GND
38	PETn5	38	GND
39	GND	39	PERp5
40	GND	40	PERn5
41	PETp6	41	GND
42	PETn6	42	GND
43	GND	43	PERp6
44	GND	44	PERn6
45	PETp7	45	GND
46	PETn7	46	GND
47	GND	47	PERp7
48	PRSn2#	48	PERn7
49	GND	49	GND
50	PETp8	50	RSVD
51	PETn8	51	GND
52	GND	52	PERp8
53	GND	53	PERn8
54	PETp9	54	GND
55	PETn9	55	GND
56	GND	56	PERp9
57	GND	57	PERn9
58	PETp10	58	GND
59	PETn10	59	GND
60	GND	60	PERp10
61	GND	61	PERn10
62	PETp11	62	GND
63	PETn11	63	GND
64	GND	64	PERp11
65	GND	65	PERn11
66	PETp12	66	GND
67	PETn12	67	GND
68	GND	68	PERp12
69	GND	69	PERn12
70	PETp13	70	GND
71	PETn13	71	GND
72	GND	72	PERp13
73	GND	73	PERn13
74	PETp14	74	GND
75	PETn14	75	GND
76	GND	76	PERp14
77	GND	77	PERn14
78	PETp15	78	GND
79	PETn15	79	GND
80	GND	80	PERp15
81	PRSn2#	81	PERn15
82	RSVD	82	GND



← I/O PANEL DIRECTION
PRIMARY (COMPONENT) SIDE



I/O PANEL DIRECTION →
PRIMARY (COMPONENT) SIDE
Add-in Card Edge-Finger Dimensions



ROMMENDED PCB LAYOUT(TOP VIEW)
DEFAULT TOLERANCE±0.05

NOTES:
 △NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND"C"
 △CHAMFER EDGES MUST BE FREE OF CUTTING BURRS TOLERANCE UNLESS OTHERWISE NOTED IS ±0.13

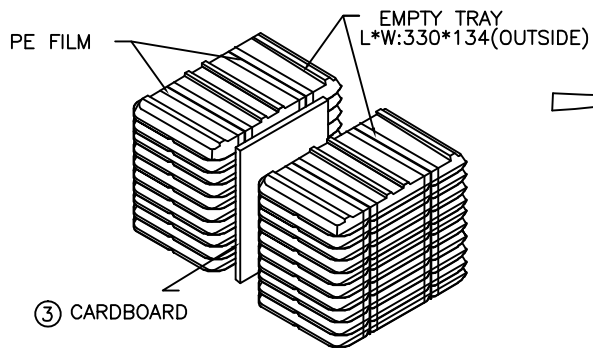
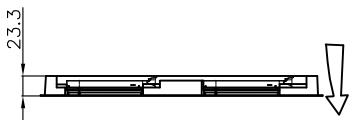
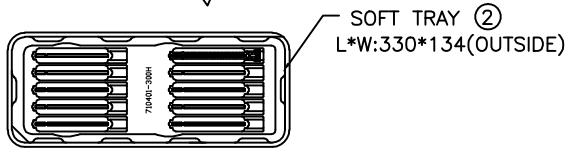
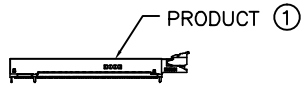
- ELECTRICAL CHARACTERISTICS :
 - CURRENT RATING:1.1AMP,30°C RISE ABOVE AMBIENT.
 - CONTACT RESISTANCE:30 MILLIOHMS MAX. INITIAL, 50 MILLIOHMS MAX. AFTER TEST.
 - INSRLATION RESISTANCE:1000 MEGOHMS MIN.
 - DIELECTRICAL WITHSTAND VOLTAGE:500V AC MIN.AT SEA LEVEL.
- MECHANICAL CHARACTERISTICS:
 - CARD INSERTION FORCE:117gf MAX.PER CONTACT PAIR.
 - DURABILITY:50 MATING AND UNMATING CYCLES.
 - CARD REMOVAL FORCE:15gf MIN.PER CONTACT PAIR.
 - CONTACT RETENTION FORCE:200gf MIN.
- ENVIRONMENTAL CHARACTERISTICS:
 - OPERATING TEMPERATURE RANGE:-40°C TO +105°C.

DIM	TOL	DIM	TOL
.x	±0.30	.x	±2'
.x	±0.25	.x	±1'
.xx	±0.20		

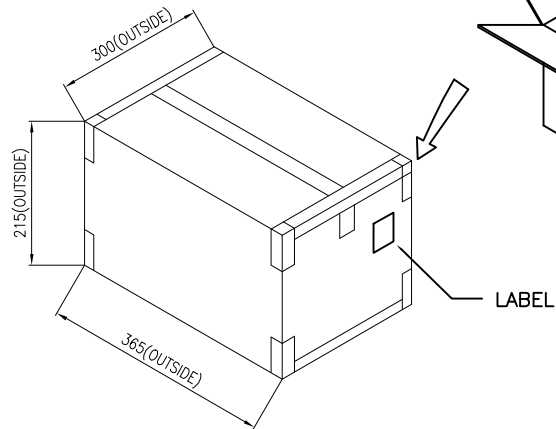
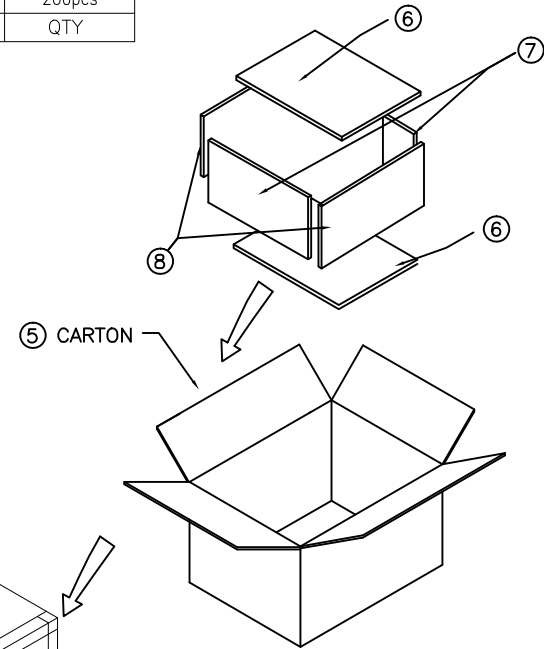
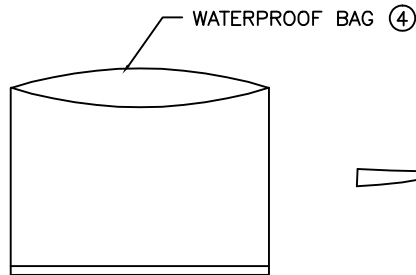
		DEREN SHENZHEN DEREN ELECTRONIC CO., LTD	
		CUSTOMER DRAWING	DATE
DRAW NO.	DESIGN:	Chen	2022.03.15
SC21072**	CHECK:	Bill.Lin	2022.03.15
REV. X1	APPROVAL:	Smark.Huo	2022.03.15
TITLE: PCI-E 5.0 SMT TYPE 164PIN WITH EAR&DIP HOOK&SHELL		P/N:	SEE TABLE
SHEET: 2/3		SCALE:	1:1 UNIT: mm

HF
Halogen Free

~~RoHS~~



8	EPE		350*160*10mm	2
7	EPE		265*180*10mm	2
6	EPE		350*285*10mm	2
5	CARTON	700101-083H	365*300*215mm	1
4	BAG	55-41001-02	600*600*0.05mm	1
3	CARDBOARD		330*165mm	1
2	SOFT TRAY	-	330*134mm	22
1	CONN	-	-	200pcs
NO.	PART NAME	PART NUMBER	SPEC.	QTY



- NOTE:
1. PUT THE PRODUCTS INTO TRAY WITH DIRECTION AS THE LEFT SKETCH SHOWN, 10pcs/TRAY, 11 TRAYS STACKED UP PER BUNDLE. THEN ADD AN EMPTY TRAY ON TOPSIDE.
 2. WIND THE TWO ENDS WITH PE FILM.
 3. PUT THE PRODUCTS BUNDLED INTO WATER-PROOF PE BAG, 2BUNDLES/BAG, THEN PUT INTO THE CARTON.
 4. SEAL OUTER CARTON WITH PACKING TAPE LIKE A 'H' SHAPE.
 5. PACKAGING QUANTITY: 200PCS/CARTON.

DIM	TOL	DIM	TOL
x.		x.	
.x		.x	
.xx			



DEREN
SHENZHEN DEREN ELECTRONIC CO., LTD

CUSTOMER DRAWING	DATE	TITLE: PCI-E 5.0 SMT TYPE 164PIN WITH EAR&DIP HOOK&SHELL
DESIGN: Chen	2022.03.15	P/N: SEE TABLE
CHECK: Bill.Lin	2022.03.15	SHEET: 3/3
REV. X1	APPROVAL: Smark.Huo	2022.03.15
		SCALE: 1:1 UNIT: mm